

## High Output Current, Rail-to-Rail Input / Output Single CMOS Operational Amplifiers

### ■ FEATURES

- AEC-Q100 Grade 1
- High output current  $\pm 100\text{mA typ. (200mA}_{\text{PP}} \text{ typ.)}$
- Operating temperature  $T_{\text{opr}} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$
- Rail-to-Rail input / output
- High EMI immunity
- Supply voltage 6.8V to 36V
- Supply current 9.5mA typ.
- Open loop gain 100dB typ.
- Input bias current 1pA typ.
- Slew rate 3.5V/ $\mu\text{s typ.}$
- Unity gain frequency 1.5MHz typ.
- Thermal shutdown
- Current limit
- Package TO-252-5-L3

### ■ APPLICATIONS

- Angle resolver
- Motor driver
- Speaker driver
- 4mA to 20mA Transmitter
- Liner power booster

### ■ DESCRIPTION

The NJU77903 is a 36V operable Rail-to-Rail input/output CMOS operational amplifier featuring an output current capacity of 200mA<sub>PP</sub> typ.

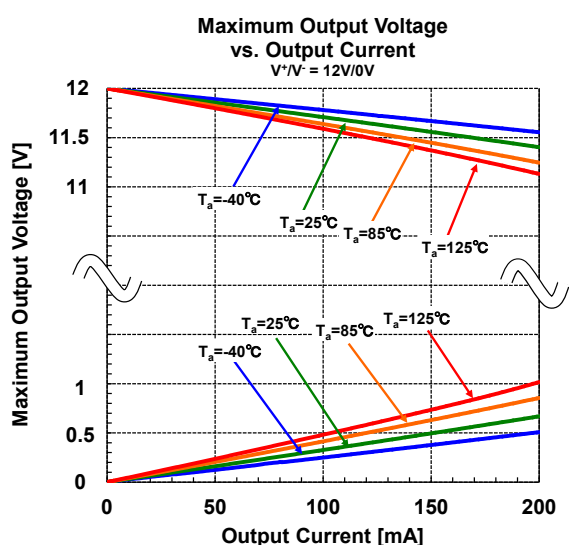
It is suitable for high voltage and high output current applications such as drive motors for hybrid and electric vehicles and resolver excitation applications that are angle detection sensors for EPS.

In such applications, high output current was supported by configuring the circuit with multiple parts such as operational amplifiers and transistors, which led to complicated circuit design and larger ECU. By using the NJU77903, it contributes to simplification of design and reduction in size and weight of the mounting board and ECU.

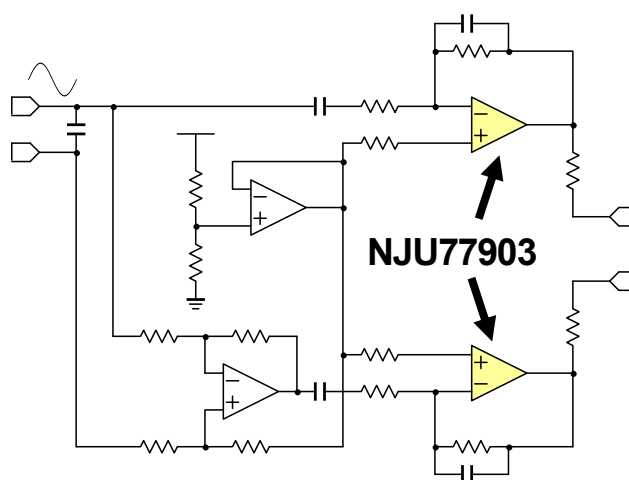
### ■ RELATED PRODUCTS

PRODUCT NAME	FEATURES
NJU7870-Z2	Resolver excitation amplifier for automobiles

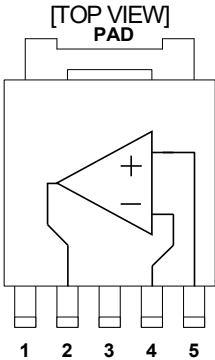
### ■ TYPICAL CHARACTERISTICS



### ■ RESOLVER EXCITATION CIRCUIT

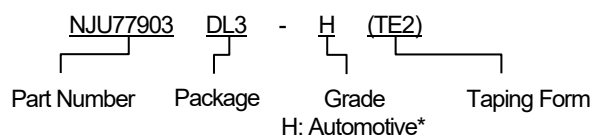


## ■ PIN CONFIGURATION

PRODUCT NAME	NJU77903DL3-H
Package	TO-252-5-L3
Pin Functions	<div style="display: flex; align-items: center;"> <div style="flex: 1;">  </div> <div style="flex: 1;"> <p>1 V<sup>+</sup></p> <p>2 OUTPUT</p> <p>3 V<sup>-</sup></p> <p>4 -INPUT</p> <p>5 +INPUT</p> </div> </div>

The PAD have to be wired as short as possible to connect with a V<sup>-</sup> terminal.

## ■ PRODUCT NAME INFORMATION



\* The detail information of automotive grades and recommended applications are described in our website.

## ■ ORDERING INFORMATION

PRODUCT NAME	PACKAGE	RoHS	HALOGEN-FREE	TERMINAL FINISH	MARKING	WEIGHT (mg)	MOQ (pcs)
NJU77903DL3-H (TE2)	TO-252-5-L3	Yes	Yes	Sn-2Bi	77903H	301	3000

## ■ ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT
Supply Voltage	$V^+ - V^-$	40	V
Differential Input Voltage <sup>(1)</sup>	$V_{ID}$	$\pm 36$	V
Input Voltage <sup>(2)</sup>	$V_{IN}$	$V^- - 0.3$ to $V^+ + 0.3$	V
Input Current	$I_{IN}$	$\pm 10$ <sup>(3)</sup>	mA
Output Terminal Input Voltage <sup>(4)</sup>	$V_O$	$V^- - 0.3$ to $V^+ + 0.3$	V
Power Dissipation <sup>(7)</sup> ( $T_a = 25^\circ\text{C}$ ) TO-252-5-L3	$P_D$	2-Layer / 4-Layer 1190 <sup>(5)</sup> / 3125 <sup>(6)</sup>	mW
Storage Temperature	$T_{stg}$	-55 to 150	$^\circ\text{C}$
Junction Temperature	$T_j$	150	$^\circ\text{C}$

## ■ THERMAL CHARACTERISTICS

PACKAGE	SYMBOL	VALUE	UNIT
Junction-to-Ambient Thermal Resistance TO-252-5-L3	$\theta_{ja}$	2-Layer / 4-Layer 105 <sup>(5)</sup> / 40 <sup>(6)</sup>	$^\circ\text{C/W}$

(1) Differential voltage is the voltage difference between +INPUT and -INPUT.

(2) Input voltage is the voltage should be allowed to apply to the input terminal independent of the magnitude of  $V^+$ . The normal operation will establish when any input is within the Common Mode Input Voltage Range of electrical characteristics.

(3) If the input voltage exceeds the supply voltage, the input current must be limited 10mA or less by using a restriction resistance.

(4) Output voltage is the voltage should be allowed to apply to the output terminal independent of the magnitude of  $V^+$ .

(5) 2-Layer: Mounted on glass epoxy board (76.2 mm × 114.3 mm × 1.6 mm: based on EIA/JEDEC standard, 2-layer FR-4), Cu area: 100 mm<sup>2</sup>.

(6) 4-Layer: Mounted on glass epoxy board (76.2 mm × 114.3 mm × 1.6 mm: based on EIA/JEDEC standard, 4-layer FR-4).

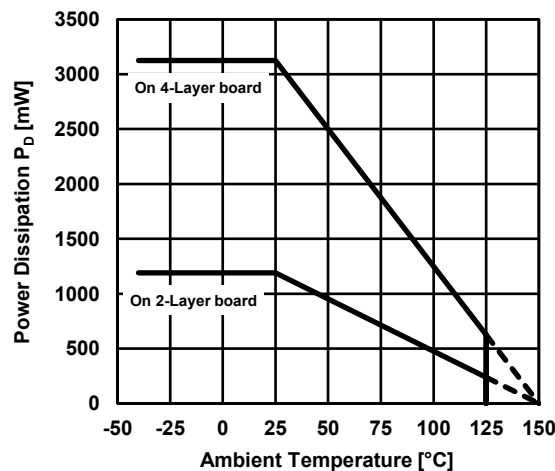
(For 4-layer: Applying 74.2 mm × 74.2 mm inner Cu area and a thermal via hole to a board based on JEDEC standard JESD51-5.)

(7) Power dissipation is the power that can be consumed by the IC at  $T_a = 25^\circ\text{C}$ , and is the typical measured value based on JEDEC condition. When using the IC over  $T_a = 25^\circ\text{C}$  subtract the value  $[\text{mW}/^\circ\text{C}] = P_D / (T_{stg}(\text{MAX}) - 25)$  per temperature.

(8) The PAD have to be wired as short as possible to connect with a  $V^-$  terminal.

## ■ POWER DISSIPATION vs. AMBIENT TEMPERATURE

TO-252-5-L3 Power Dissipation vs. Temperature

 $T_{opr} = -40^\circ\text{C}$  to  $125^\circ\text{C}$ ,  $T_j = 150^\circ\text{C}$ 


## ■ RECOMMENDED OPERATING CONDITIONS

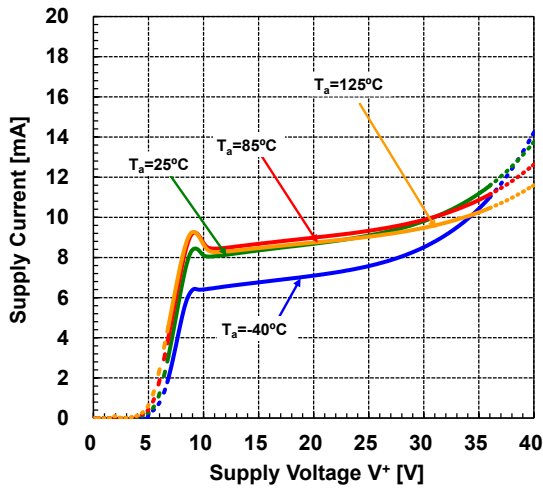
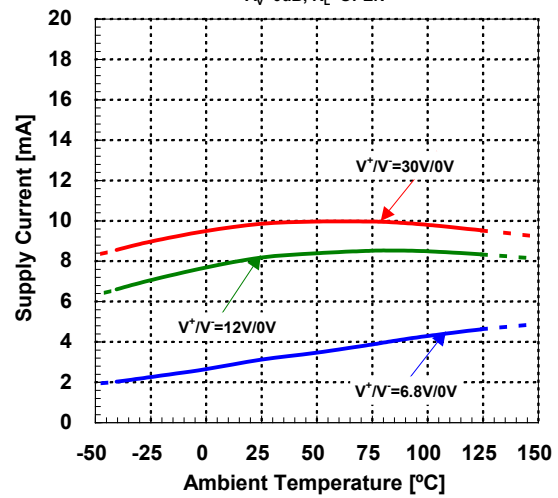
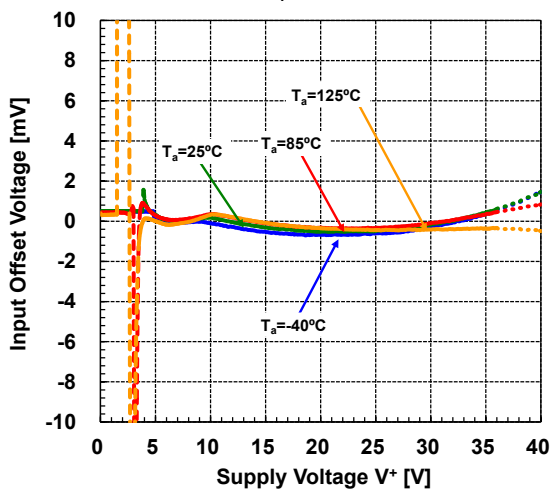
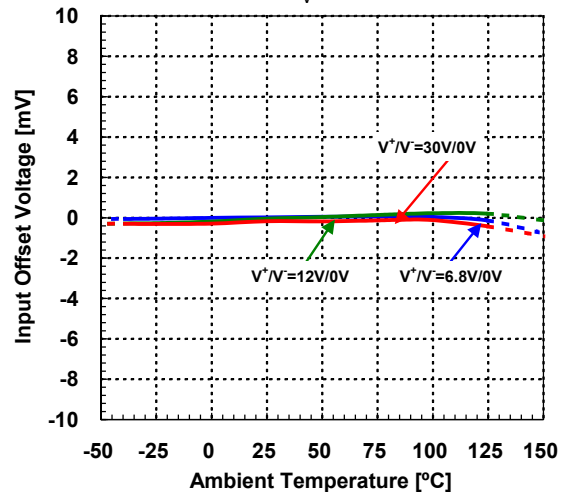
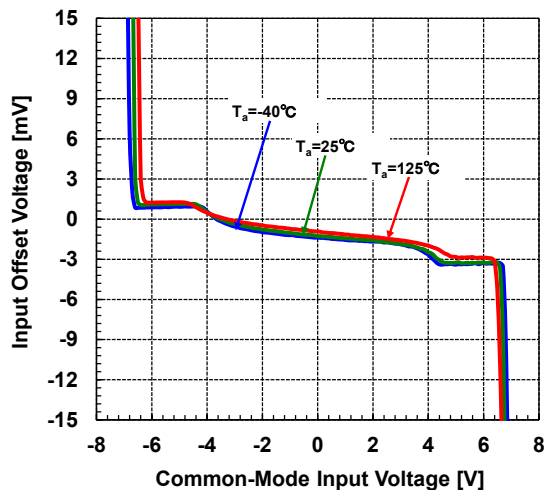
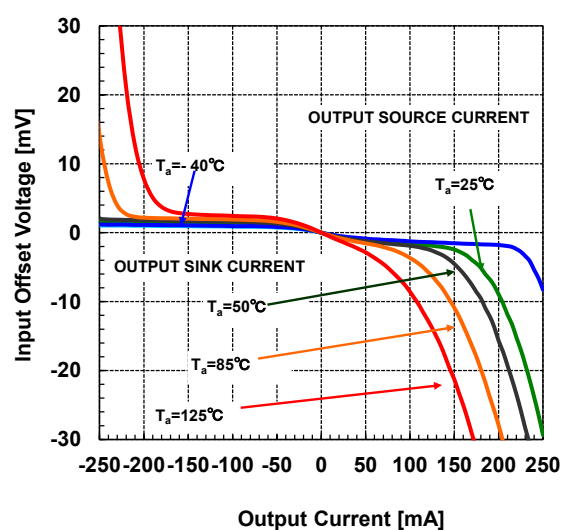
PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	$V^+ - V^-$	6.8 to 36	V
Operating Temperature	$T_{opr}$	-40 to 125	$^\circ\text{C}$

**■ ELECTRICAL CHARACTERISTICS** ( $V^+ = 12V$ ,  $V^- = 0V$ ,  $V_{IC} = 6V$ ,  $R_L = 10k\Omega$ ,  $T_a = 25^\circ C$ , unless otherwise noted.)

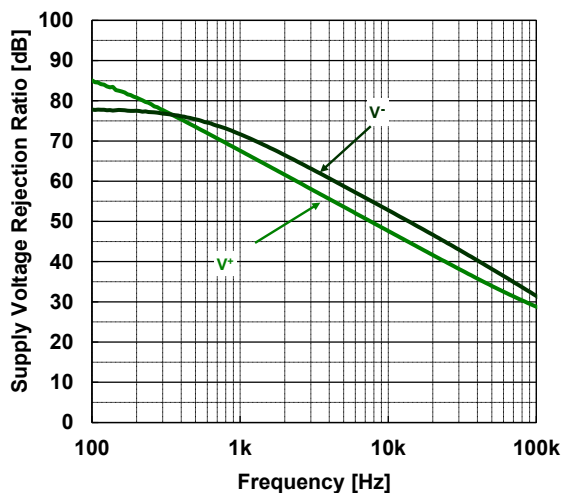
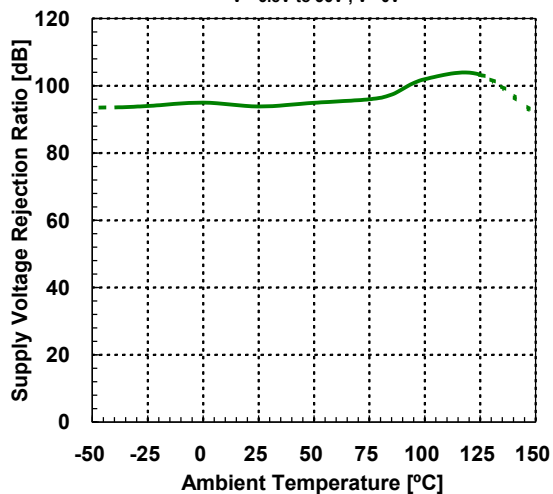
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
INPUT CHARACTERISTICS						
Input Offset Voltage	V <sub>IO</sub>	R <sub>S</sub> = 50Ω	-	1	6	mV
		R <sub>S</sub> = 50Ω, T <sub>a</sub> = -40°C to 125°C	-	-	15	
Input Offset Voltage Drift	ΔV <sub>IO</sub> /ΔT	T <sub>a</sub> = -40°C to 125°C	-	20	-	μV/°C
Input Bias Current	I <sub>B</sub>		-	1	-	pA
Input Offset Current	I <sub>IO</sub>		-	1	-	pA
Open Loop Gain	A <sub>V</sub>	V <sub>O</sub> = 1V to 11V, R <sub>L</sub> = 10kΩ to V <sup>+</sup> /2	80	100	-	dB
		V <sub>O</sub> = 1V to 11V, R <sub>L</sub> = 10kΩ to V <sup>+</sup> /2, T <sub>a</sub> = -40°C to 125°C	75	-	-	
Common Mode Rejection Ratio	CMR	V <sub>IC</sub> = 0V to 6V, V <sub>IC</sub> = 6V to 12V	55	75	-	dB
		V <sub>IC</sub> = 0V to 6V, V <sub>IC</sub> = 6V to 12V, T <sub>a</sub> = -40°C to 125°C	50	-	-	
Common Mode Input Voltage Range	V <sub>ICM</sub>	CMR ≥ 55dB	0	-	12	V
		CMR ≥ 50dB, T <sub>a</sub> = -40°C to 125°C	0	-	12	
OUTPUT CHARACTERISTICS						
Output Voltage	V <sub>OH</sub>	R <sub>L</sub> = 10kΩ to V <sup>+</sup> /2	11.97	11.99	-	V
		R <sub>L</sub> = 10kΩ to V <sup>+</sup> /2, T <sub>a</sub> = -40°C to 125°C	11.97	-	-	
		I <sub>SOURCE</sub> = 100mA	11.40	11.65	-	
		I <sub>SOURCE</sub> = 100mA, T <sub>a</sub> = -40°C to 125°C	11.20	-	-	
	V <sub>OL</sub>	R <sub>L</sub> = 10kΩ to V <sup>+</sup> /2	-	0.01	0.03	V
		R <sub>L</sub> = 10kΩ to V <sup>+</sup> /2, T <sub>a</sub> = -40°C to 125°C	-	-	0.03	
		I <sub>SINK</sub> = 100mA	-	0.35	0.60	
		I <sub>SINK</sub> = 100mA, T <sub>a</sub> = -40°C to 125°C	-	-	0.80	
Output Source Current Limit	I <sub>SOURCE LIM</sub>		-	375	700	mA
		T <sub>a</sub> = -40°C to 125°C	-	-	700	
Output Sink Current Limit	I <sub>SINK LIM</sub>		-	375	700	mA
		T <sub>a</sub> = -40°C to 125°C	-	-	700	
POWER SUPPLY						
Supply Current	I <sub>DD</sub>	No Signal, R <sub>L</sub> = OPEN	-	9.5	12.5	mA
		No Signal, R <sub>L</sub> = OPEN, T <sub>a</sub> = -40°C to 125°C	-	-	12.5	
Supply Voltage Rejection Ratio	SVR	V <sup>+</sup> = 6.8V to 36V	70	85	-	dB
		V <sup>+</sup> = 6.8V to 36V, T <sub>a</sub> = -40°C to 125°C	65	-	-	
DYNAMIC PERFORMANCE						
Unity Gain Frequency	f <sub>T</sub>	R <sub>L</sub> = 10kΩ to V <sup>+</sup> /2, C <sub>L</sub> = 10pF	-	1.5	-	MHz
Phase Margin	Φ <sub>M</sub>	R <sub>L</sub> = 10kΩ to V <sup>+</sup> /2, C <sub>L</sub> = 10pF	-	75	-	deg
Slew Rate <sup>(9)</sup>	SR	G <sub>V</sub> = 0dB, R <sub>L</sub> = 10kΩ to V <sup>+</sup> /2, C <sub>L</sub> = 10pF, V <sub>IN</sub> = 4V <sub>PP</sub> (4V to 8V)	2.5	3.5	-	V/μs
		G <sub>V</sub> = 0dB, R <sub>L</sub> = 10kΩ to V <sup>+</sup> /2, C <sub>L</sub> = 10pF, V <sub>IN</sub> = 4V <sub>PP</sub> (4V to 8V), T <sub>a</sub> = -40°C to 125°C	2.0	-	-	
NOISE PERFORMANCE						
Equivalent Input Noise Voltage	e <sub>n</sub>	f = 10kHz, R <sub>S</sub> = 50Ω	-	50	-	nV/√Hz
Total Harmonic Distortion +Noise	THD+N	G <sub>V</sub> = 6dB, R <sub>F</sub> = 10kΩ, R <sub>L</sub> = 10kΩ, C <sub>L</sub> = 10pF, V <sub>O</sub> = 2V <sub>PP</sub> , f = 10kHz	-	0.03	-	%

(9) Number specified is the slower of the positive and negative slew rates

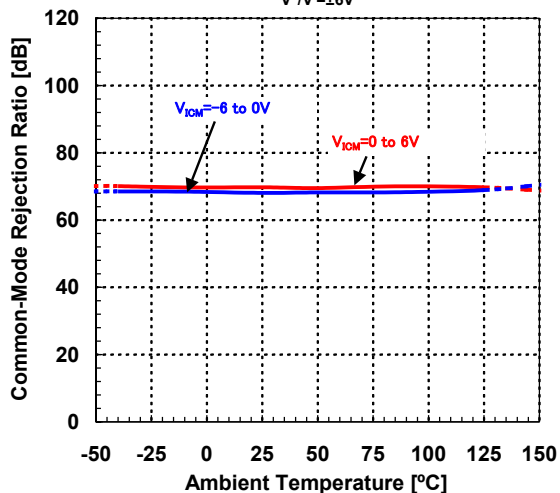
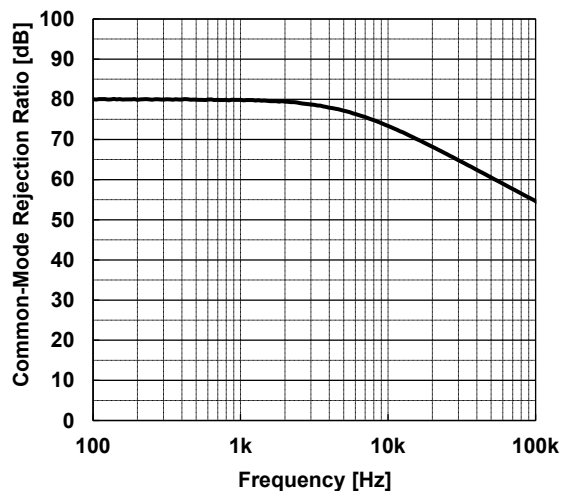
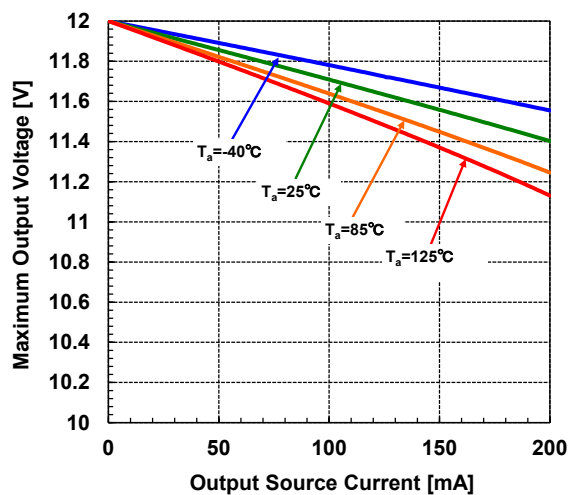
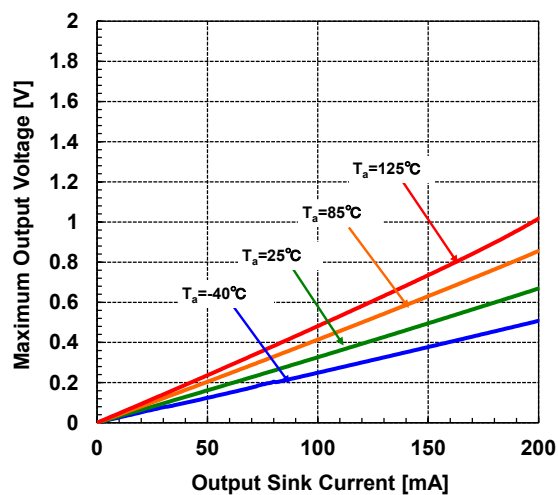
## ■ TYPICAL CHARACTERISTICS

Supply Current vs. Supply Voltage  
 $A_V=0\text{dB}$ ,  $R_L=\text{OPEN}$ ,  $V=0\text{V}$ Supply Current vs. Temperature  
 $A_V=0\text{dB}$ ,  $R_L=\text{OPEN}$ Input Offset Voltage vs. Supply Voltage  
 $A_V=0\text{dB}$ ,  $V=0\text{V}$ Input Offset Voltage vs. Temperature  
 $A_V=0\text{dB}$ Input Offset Voltage  
vs. Common-Mode Input Voltage  
 $V^+/V^-=\pm 6\text{V}$ Input Offset Voltage vs. Output Current  
 $V^+/V^-=\pm 6\text{V}$ 

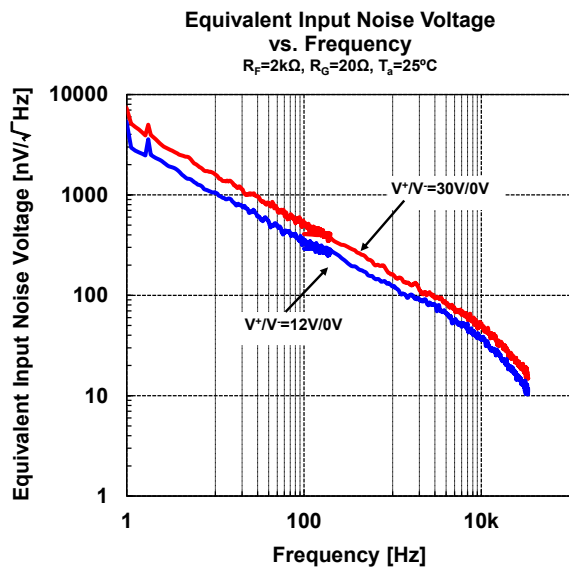
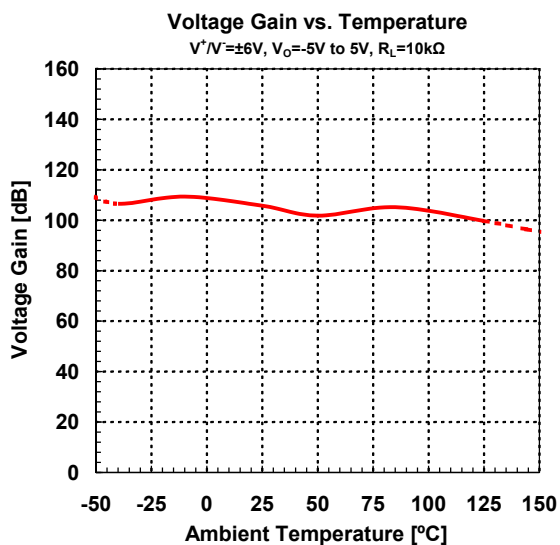
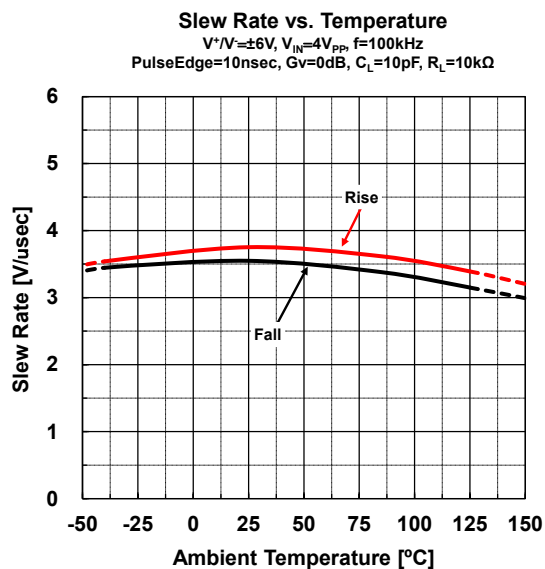
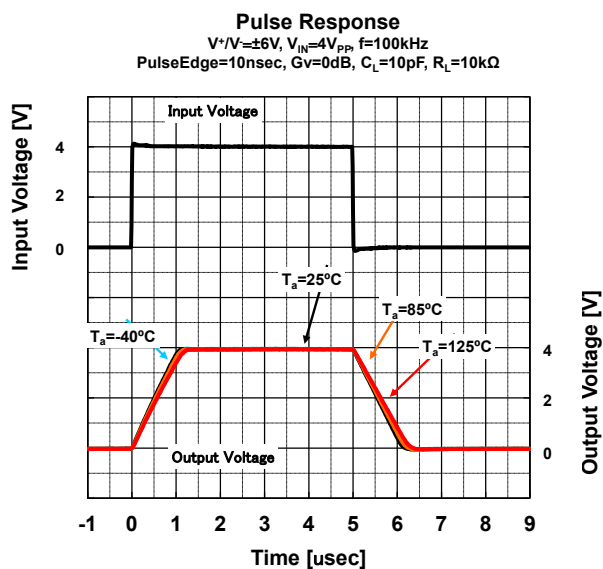
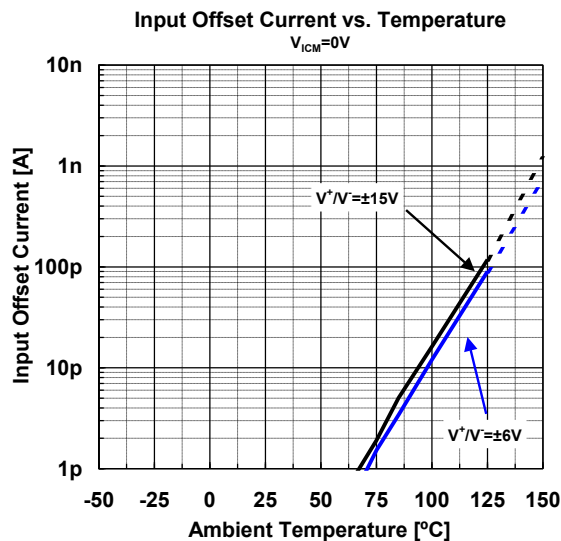
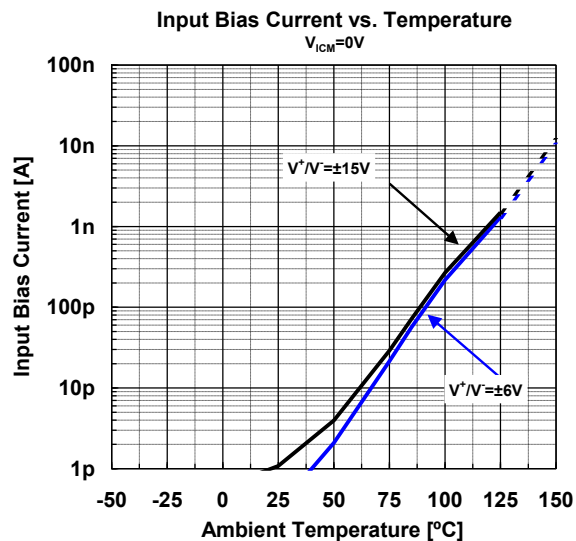
## ■ TYPICAL CHARACTERISTICS

Supply Voltage Rejection Ratio  
vs. Frequency $V^+/V^- = 12V/0V$ ,  $V_{IN} = 2V_{PP}$ ,  $G_V = 40dB$ ,  $R_S = 1k\Omega$ ,  $R_F = 100k\Omega$ ,  $T_a = 25^\circ C$ Supply Voltage Rejection Ratio  
vs. Temperature $V^+ = 6.8V$  to  $36V$ ,  $V^- = 0V$ 

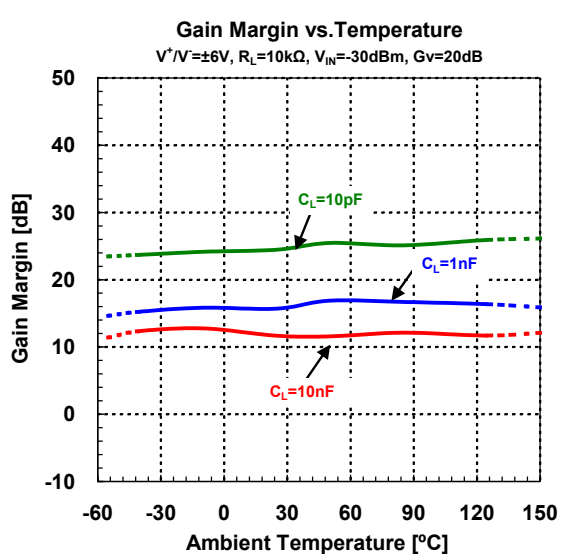
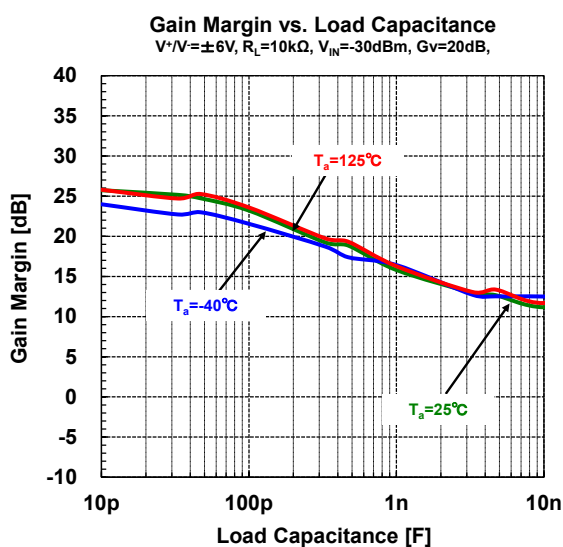
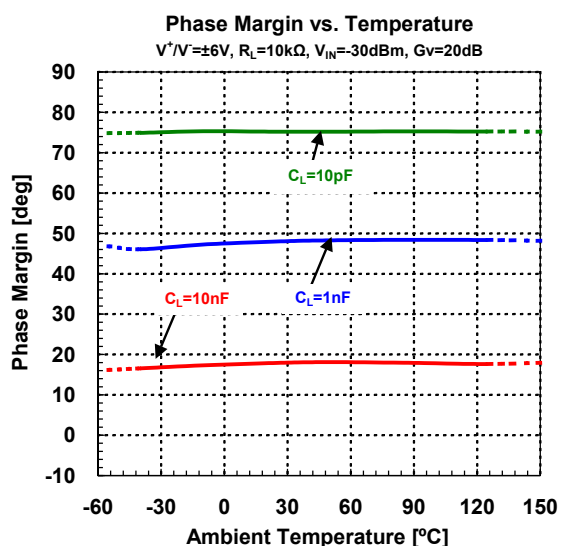
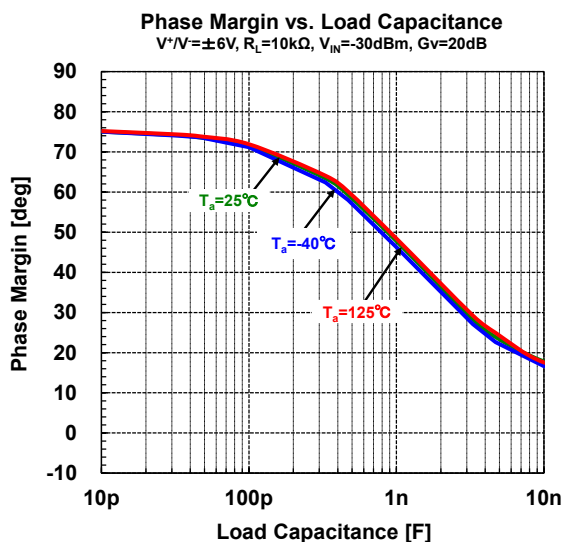
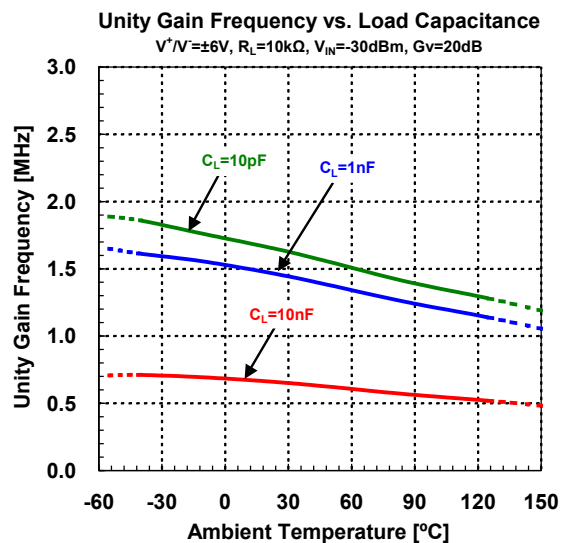
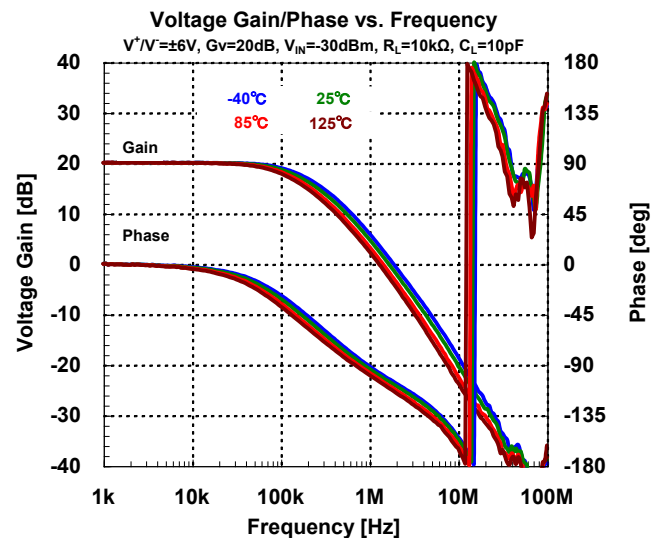
Common-Mode Rejection Ratio vs. Temperature

 $V^+/V^- = \pm 6V$ Common-Mode Rejection Ratio  
vs. Frequency $V^+/V^- = \pm 6V$ ,  $V_{IN} = 3V_{PP}$ ,  $G_V = 40dB$ ,  $R_S = 1k\Omega$ ,  $R_F = 100k\Omega$ ,  $T_a = 25^\circ C$ Maximum Output Voltage  
vs. Output Source Current $V^+/V^- = 12V/0V$ Maximum Output Voltage  
vs. Output Sink Current $V^+/V^- = 12V/0V$ 

## ■ TYPICAL CHARACTERISTICS

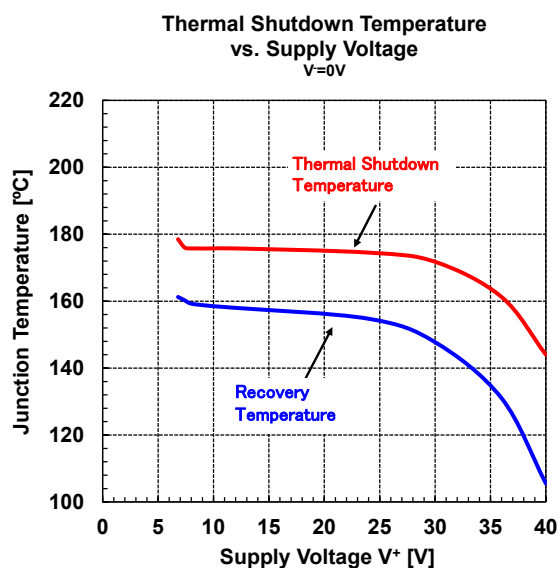
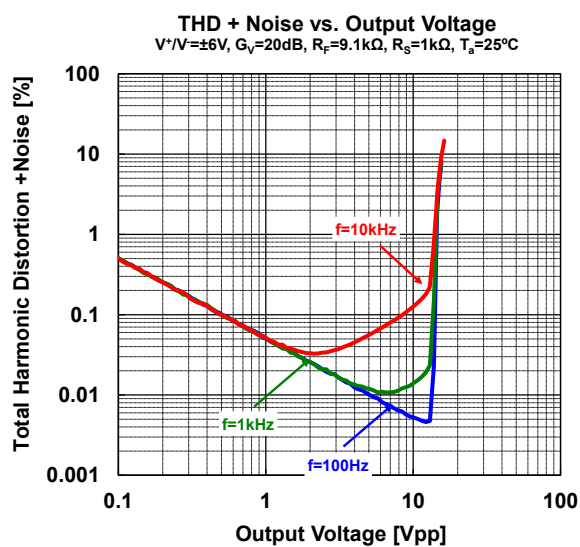
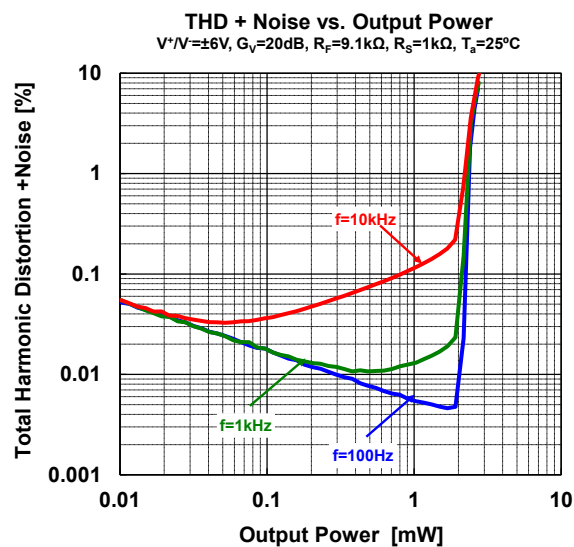


## ■ TYPICAL CHARACTERISTICS

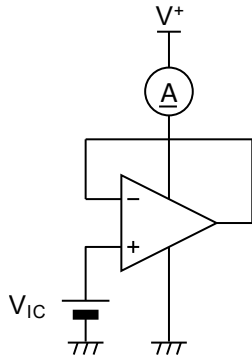
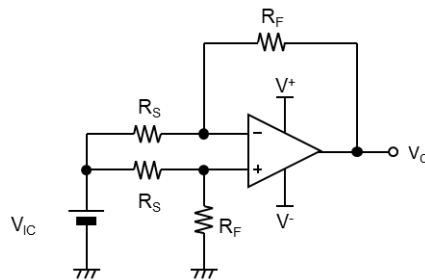




## ■ TYPICAL CHARACTERISTICS



## ■ TEST CIRCUITS

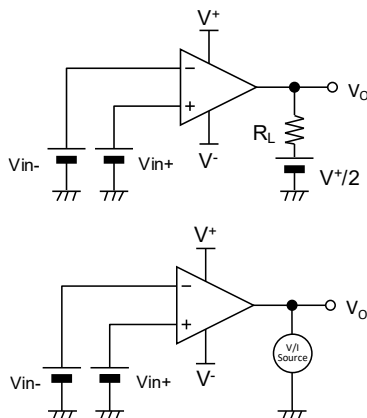
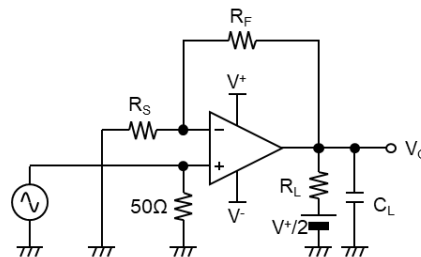
•  $I_{DD}$ •  $V_{IO}$ , CMR, SVR
 $R_S = 50\Omega$ ,  $R_F = 50k\Omega$ 


$$V_{IO} = \frac{R_S}{(R_S + R_F)} \times (V_O - V_{IC})$$

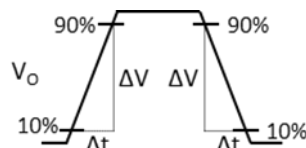
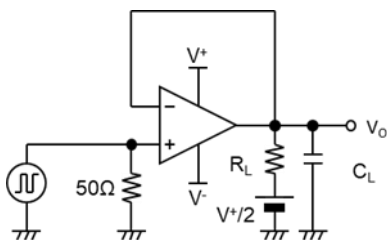
$$CMR = 20 \log \frac{\Delta V_{IC} \left(1 + \frac{R_F}{R_S}\right)}{\Delta V_O}$$

$$SVR = 20 \log \frac{\Delta V_S \left(1 + \frac{R_F}{R_S}\right)}{\Delta V_O}$$

$$V_S = V^+ - V^-$$

•  $V_{OH}$ ,  $V_{OL}$ 
 $V_{OH}$ ;  $V_{in+} = V^+/2 + 1V$ ,  $V_{in-} = V^+/2$ 
 $V_{OL}$ ;  $V_{in+} = V^+/2$ ,  $V_{in-} = V^+/2 + 1V$ 
•  $f_r$ 
 $R_L = 10k\Omega$ ,  $C_L = 10pF$ 


## • SR

 $R_L = 10k\Omega$ ,  $C_L = 10pF$ 


$$SR = \frac{\Delta V}{\Delta t}$$

**■ APPLICATION NOTE**

The NJU77903 is CMOS operational amplifier that combines rail-to-rail input and output with operating up to 36V. It is able to output high current without the power booster. Therefore, the NJU77903 is suitable for the application requires high operating voltage and high output current.

This application note is one of effectual measures for understanding the dissipation power, thermal shutdown and behavior of current limit, to avoiding unexpected troubles. This application note consists of following matter.

1. Calculation of dissipation power
2. Thermal shutdown
3. Current limit
4. Resolver Excitation Circuit
5. Input Overvoltage Protection

This description does not assure the actual behavior. The performance of the NJU77903 should be conducted trials using actual equipment.

## 1. Calculation of dissipation power

The dissipation power is determined by the type of loads. It in case of resistance load and inductance load are shown respectively on this note. The symbols of supply voltage are defined as  $V_{DD}$  and  $V_{SS}$  instead of  $V^+$  and  $V^-$ .

### 1.1 Calculation of dissipation power with resistance load

The dissipation power from the time 0 to  $\pi$  and it from  $\pi$  to  $2\pi$  are calculated separately.

#### $t = 0$ to $\pi$

Fig.1.1 shows the internal current from 0 to  $\pi$ , Fig.1.2 shows the output current and the output voltage from 0 to  $\pi$ .  $I_O$  is the output current and  $I_A$  is the current with the exception of the output current. The dissipation power from 0 to  $\pi$  is expressed by the following equation.

$$\begin{aligned} P_{R1} &= (V_{DD} - V_{SS})I_A + \frac{1}{\pi} \int_0^{\pi} (V_{DD} - V_O \sin \theta) I_O \sin \theta d\theta \\ &= (V_{DD} - V_{SS})I_A + \frac{1}{\pi} \int_0^{\pi} (V_{DD} - V_O \sin \theta) \frac{V_O}{R} \sin \theta d\theta \\ &= (V_{DD} - V_{SS})I_A + \frac{2V_{DD}V_O}{\pi R} - \frac{V_O^2}{2R} \end{aligned}$$

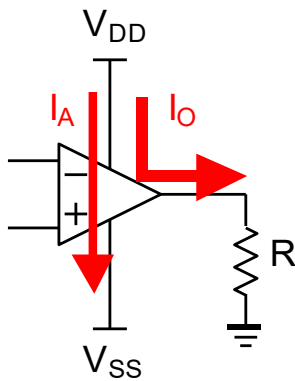


Fig.1.1 The internal current from 0 to  $\pi$

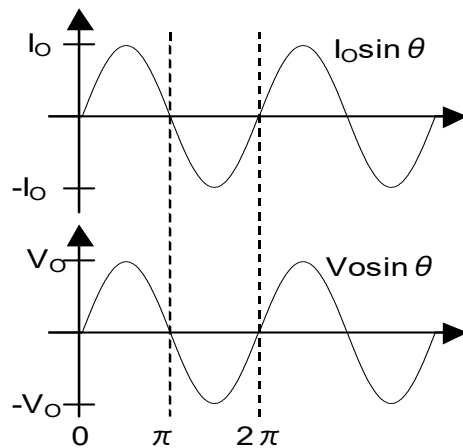


Fig.1.2 The output current and voltage with resistance load

$t = \pi$  to  $2\pi$

Fig.1.3 shows the internal current from  $\pi$  to  $2\pi$ , the dissipation power from  $\pi$  to  $2\pi$  is expressed by the following equation.

$$\begin{aligned} P_{R2} &= (V_{DD} - V_{SS})I_A + \frac{1}{\pi} \int_{\pi}^{2\pi} (V_O \sin \theta - V_{SS}) I_O \sin \theta d\theta \\ &= (V_{DD} - V_{SS})I_A + \frac{1}{\pi} \int_{\pi}^{2\pi} (V_O \sin \theta - V_{SS}) \frac{V_O}{R} \sin \theta d\theta \\ &= (V_{DD} - V_{SS})I_A - \frac{2V_{SS}V_O}{\pi R} - \frac{V_O^2}{2R} \end{aligned}$$

In the case of  $V_{DD} = -V_{SS}$ , the internal loss  $P_R$  is the following result.

$$P_R = (V_{DD} - V_{SS})I_A + \frac{2V_{DD}V_O}{\pi R} - \frac{V_O^2}{2R}$$

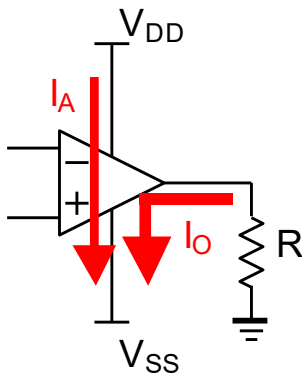


Fig.1.3 The internal current from  $\pi$  to  $2\pi$

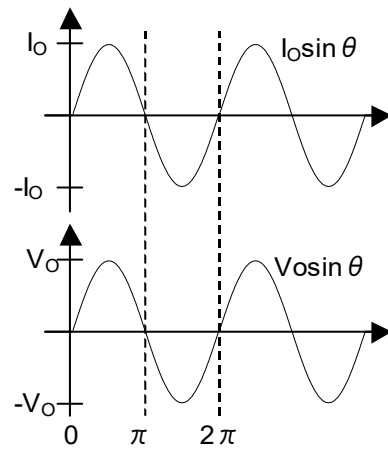


Fig.1.4 The output current and voltage with resistance load

### Example for use

The dissipation power is calculated on the following condition.

Condition:

$$V_{DD}/V_{SS} = 6V/-6V$$

$$V_O = 1V_{PK}$$

$$R = 20\Omega (I_O = 1V_{PK}/20\Omega = 50mA_{PK} = 100mA_{PP})$$

$$I_A = 1.5mA$$

$$\begin{aligned} P_R &= (V_{DD} - V_{SS})I_A + \frac{2V_{DD}V_O}{\pi R} - \frac{V_O^2}{2R} \\ &= (6V + 6V) \times 1.5mA + \frac{2 \times 6V \times 1V}{\pi \times 20\Omega} - \frac{(1V)^2}{2 \times 20\Omega} = 184mW \end{aligned}$$

On the single power supply operation ( $V_{DD}/V_{SS} = 12V/0V$ ) with the load resistance ( $R = 20\Omega$  which is the middle point Voltage), the dissipation power is 184mW. It is same as previous one.

## 1.2 Calculation of dissipation power with inductance load

The dissipation power from the time 0 to  $\pi$  and it from  $\pi$  to  $2\pi$  are calculated separately.

### $t = 0$ to $\pi$

Fig.1.5 shows the internal current from 0 to  $\pi$  and Fig.1.7 shows the output current and the output Voltage from 0 to  $\pi$ . Since it is an inductance load, the output current and the output voltage make 90-degree phase difference.  $I_O$  is the output current and  $I_A$  is the current with the exception of the output current. The loss by output current from 0 to  $\pi$  is expressed by the following equation.

$$P_{LO1} = (V_{DD} - V_O \cos \theta) I_O \sin \theta = V_{DD} I_O \sin \theta - \frac{1}{2} V_O I_O \sin 2\theta$$

The loss by output current from 0 to  $\pi$  is expressed by the following equation.

$$\begin{aligned} P_{L1} &= (V_{DD} - V_{SS}) I_A + \frac{1}{\pi} \int_0^\pi V_{DD} I_O \sin \theta d\theta - \frac{1}{\pi} \int_0^\pi \frac{1}{2} V_O I_O \sin 2\theta d\theta \\ &= (V_{DD} - V_{SS}) I_A + \frac{2V_{DD} I_O}{\pi} \end{aligned}$$

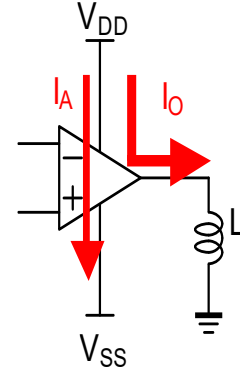


Fig.1.5 The internal current from 0 to  $\pi$

### $t = \pi$ to $2\pi$

Fig.1.6 shows the internal current from  $\pi$  to  $2\pi$ . The loss by output current from  $\pi$  to  $2\pi$  is expressed by the following equation.

$$P_{LO2} = (V_O \cos \theta - V_{SS}) I_O \sin \theta = -V_{SS} I_O \sin \theta + \frac{1}{2} V_O I_O \sin 2\theta$$

The Dissipation power from  $\pi$  to  $2\pi$  is expressed by the following equation.

$$P_{L2} = (V_{DD} - V_{SS}) I_A + \frac{1}{\pi} \int_\pi^{2\pi} -V_{SS} I_O \sin \theta d\theta + \frac{1}{\pi} \int_\pi^{2\pi} \frac{1}{2} V_O I_O \sin 2\theta d\theta = (V_{DD} - V_{SS}) I_A - \frac{2V_{SS} I_O}{\pi}$$

In the case of  $V_{DD} = -V_{SS}$ , the dissipation power is the following result.

$$P_L = (V_{DD} - V_{SS}) I_A + \frac{2V_{DD} I_O}{\pi}$$

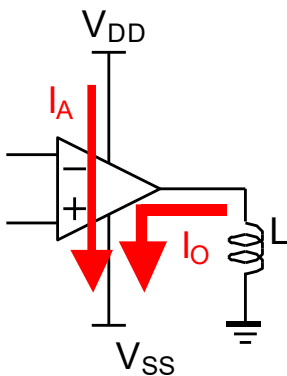


Fig.1.6 The internal current from  $\pi$  to  $2\pi$

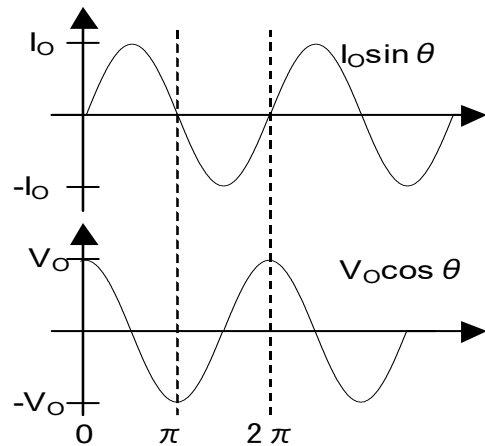


Fig.1.7 The output current and output voltage with inductance load

**Example for use**

The dissipation power is calculated on the following condition.

Condition:

$$V_{DD}/V_{SS} = 6V/-6V$$

$$I_O = 50mA_{PK} (100mA_{PP})$$

$$I_A = 1.5mA$$

$$P_L = (V_{DD} - V_{SS})I_A + \frac{2V_{DD}I_O}{\pi} = (6V + 6V) \times 1.5mA + \frac{2 \times 6V \times 50mA}{\pi} = 209mW$$

On the Single power supply operation whose equivalent circuit is Fig.1.8, the dissipation power is as follows.

Condition:

$$V_{DD}/V_{SS} = 12V/0V$$

$$I_O = 50mA_{PK} (100mA_{PP})$$

$$I_A = 1.5mA$$

$$P_L = (V_{DD} - V_{SS})I_A + \frac{2V_{DD}I_O}{\pi} = (6V + 6V) \times 1.5mA + \frac{2 \times (12V/2) \times 50mA}{\pi} = 209mW$$

Fig.1.9 is the supply-voltage dependency of the dissipation power on inductance load. The NJU77903 should be operated in lower than package power ( $P_D$ ).

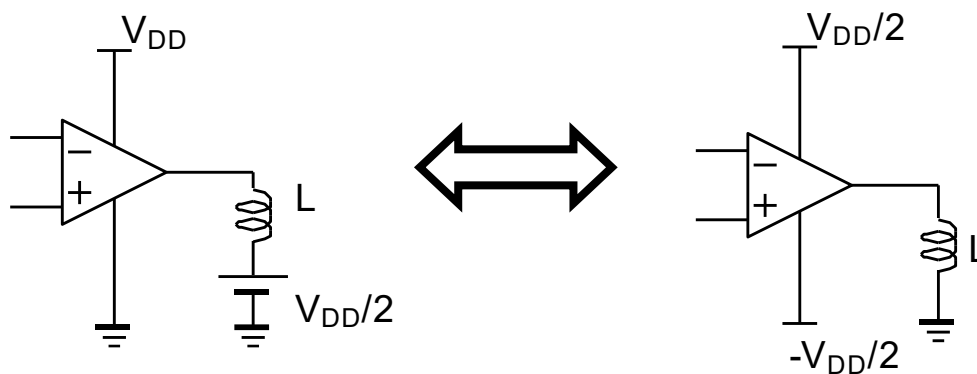


Fig.1.8 Equivalent circuit (Single Supply and Dual Supply)

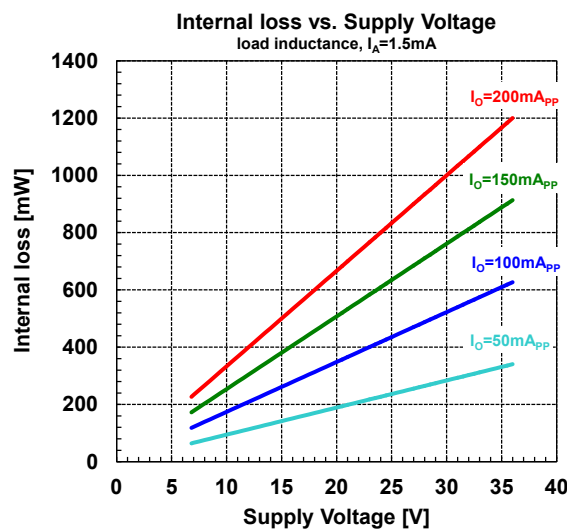


Fig.1.9 The supply voltage dependency of the dissipation power by inductance load. (Single-Supply)

### 1.3 The current with the exception of the Output current

Fig.1.10 shows the evaluation circuit of the current with the exception of the output current. This result shows Fig1.11 and Fig.1.12.

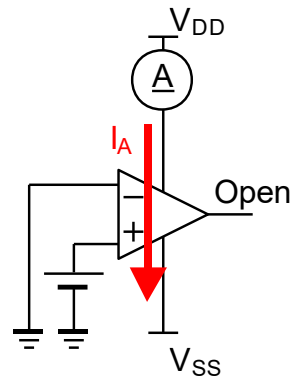


Fig.1.10 The current with the exception of the output current

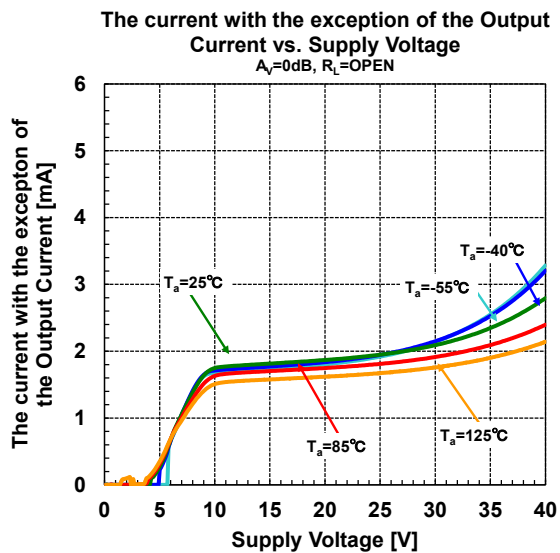


Fig.1.11 The current with the exception of the Output current vs. Supply Voltage

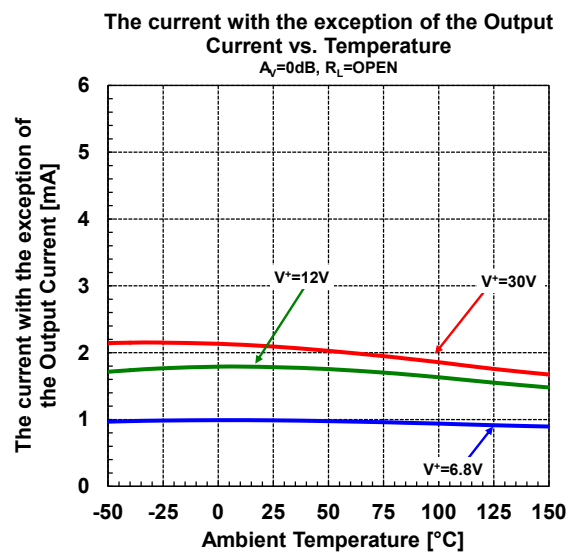


Fig.1.12 The current with the exception of the Output current vs. Temperature



## 2. Thermal Shutdown

The NJU77903 has thermal shutdown (TSD) function in case that dissipation power exceeds package power  $P_D$ . Fig.2.1 shows Thermal Shutdown Temperature vs. Supply Voltage. When the junction temperature exceeds the shutdown temperature approximately 175°C on the supply voltage 12V, the TSD function operates and disables the output current. Under the TSD operation, the output terminal is regarded as high impedance terminal. If the output voltage is necessarily GND Voltage, the output terminal should be connected to GND via resistance.

When the junction temperature cools to recovery temperature approximately 160°C on the supply voltage 12V, the NJU77903 automatically recover from the TSD operation and output current is re-enabled.

The TSD function is not intended to replace proper heat sinking. The NJU77903 should be operated in lower than 150°C the maximum junction temperature.

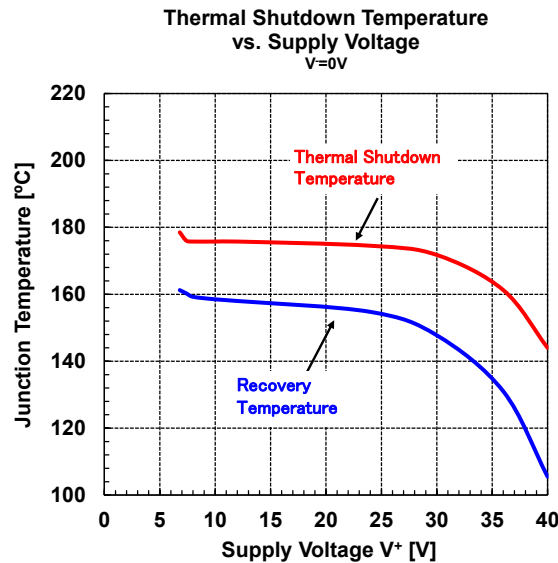


Fig.2.1 Thermal Shutdown Temperature vs. Supply Voltage

### 3. Current Limit

The NJU77903 is designed with internal current limit in case of overload condition. Fig.3.1 shows the Output Source Current Limit vs. temperature and Fig.3.2 shows the Output Sink Current Limit vs. temperature respectively. With the increasing in temperature, the limits are reduced.

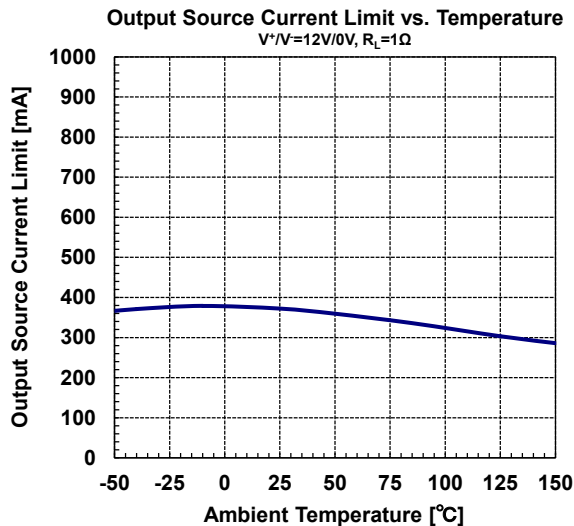


Fig.3.1 Output Source Current Limit vs. Temperature

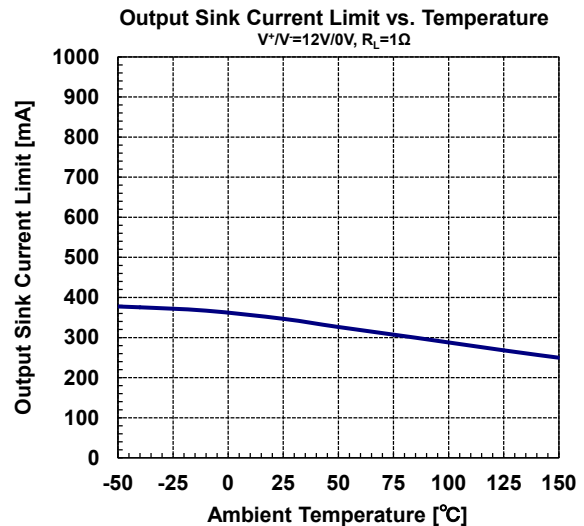


Fig.3.2 Output Sink Current Limit vs. Temperature

Fig.3.3 shows Output Source Current vs. time. Output Source Current Limit decreases gradually since junction temperature rises. The output current is temporarily disabled due to TSD operation in  $T_a = 150^\circ\text{C}$  line of Fig.3.3 (time = 55msec to 75msec). When the junction temperature falls, the output current is automatically recovered (time = 75msec to 100msec). In order to prevent from damage the NJU77903 should be running under maximum junction temperature.

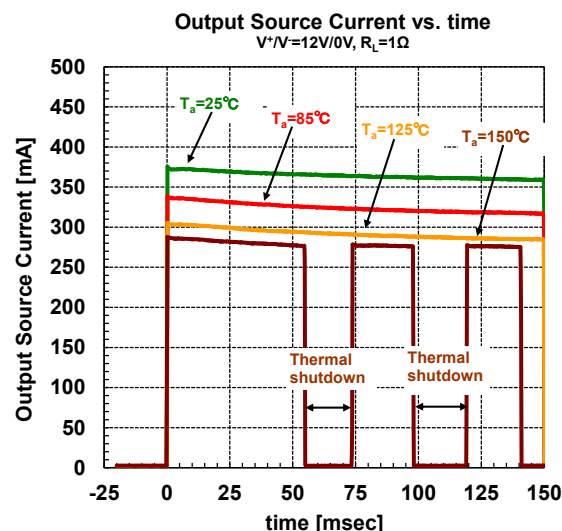


Fig.3.3 Output Source Current Limit vs. Time



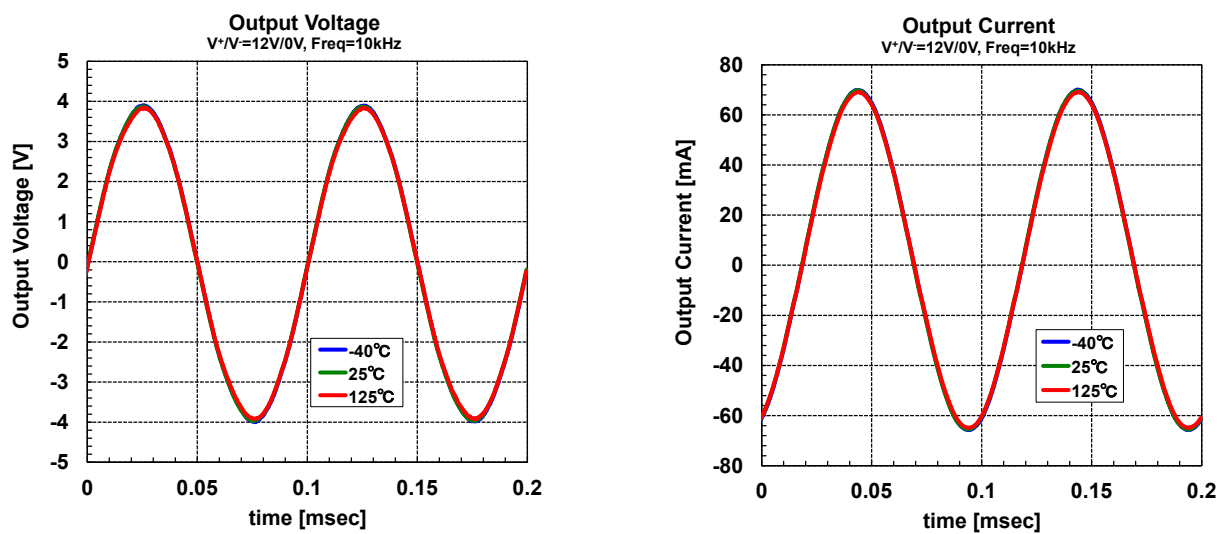
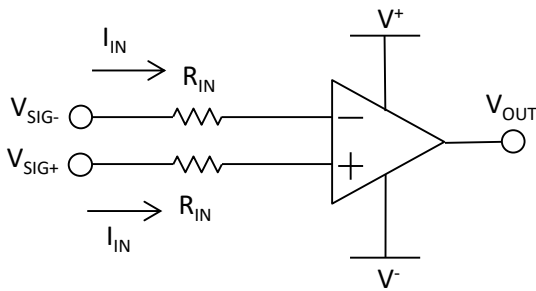


Fig.4.4 Output Voltage and Output Current of Resolver Excitation Circuit

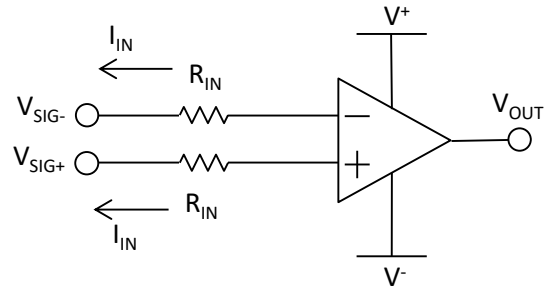
### 5. Input Overvoltage Protection

If the input voltage exceeds the supply rail, you must use a limiting resistor as shown in Fig.5.1, because you must be limited to less than the input current of absolute maximum ratings. Resistance value of the current limiting and can be calculated by the following equation.



$$I_{IN} = \frac{V_{SIG} - V^+}{R_{IN}} \leq 10\text{mA}, (V_{SIG} > V^+)$$

Fig.5.1a Input Overvoltage ( $V_{SIG} > V^+$ )

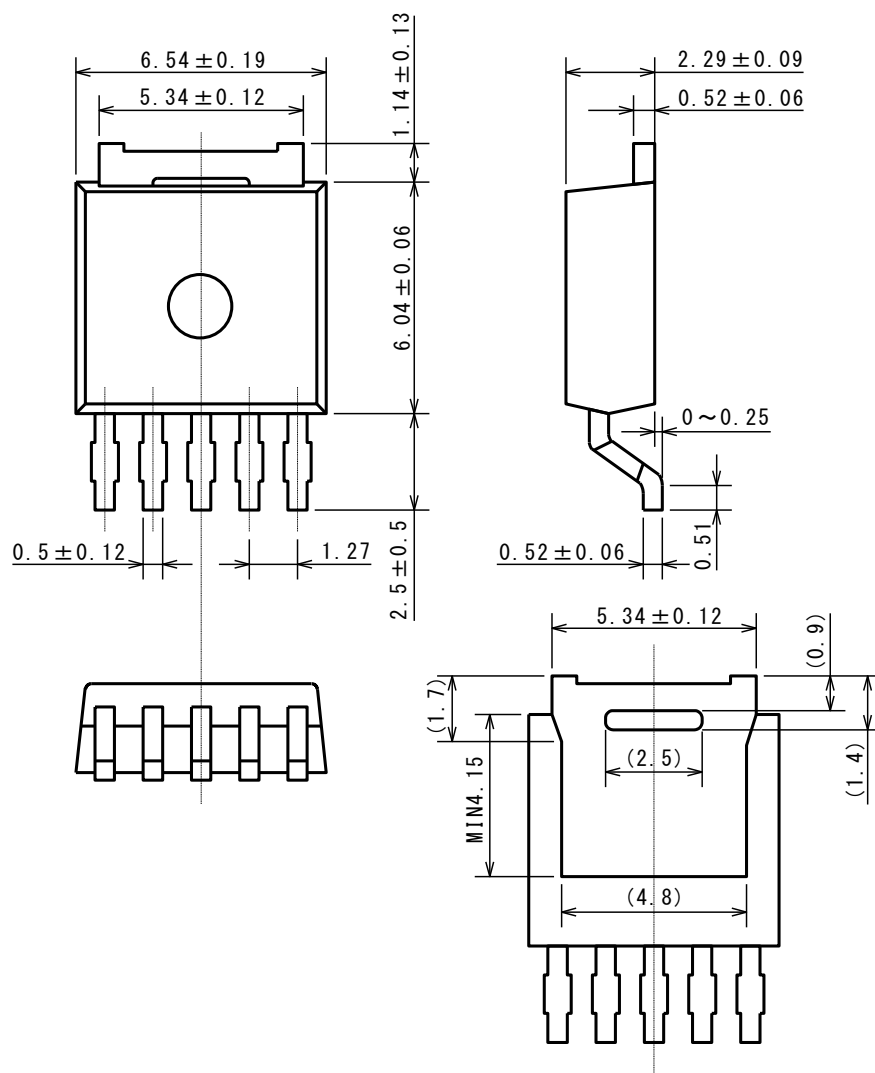


$$I_{IN} = \frac{V^- - V_{SIG}}{R_{IN}} \leq 10\text{mA}, (V_{SIG} < V^-)$$

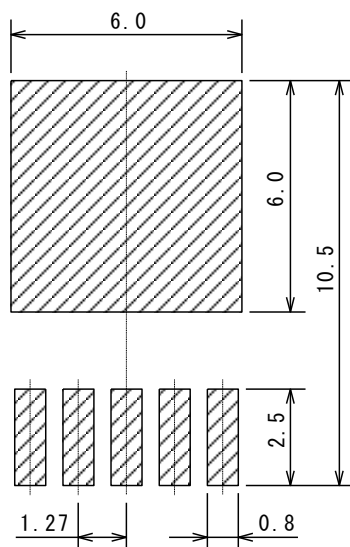
Fig.5.1b Input Overvoltage ( $V_{SIG} < V^-$ )

## ■ PACKAGE DIMENSIONS

Unit: mm

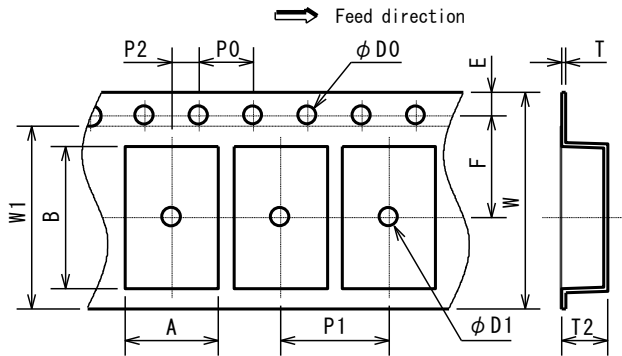


## ■ EXAMPLE OF SOLDER PADS DIMENSIONS



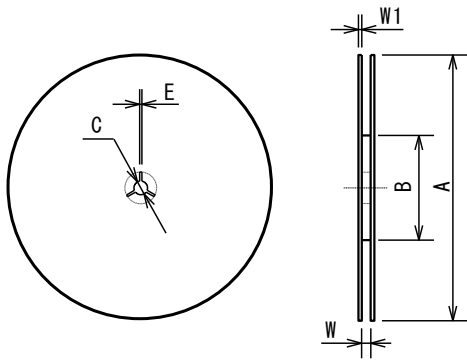
■ PACKING SPEC  
TAPING DIMENSIONS

Unit: mm



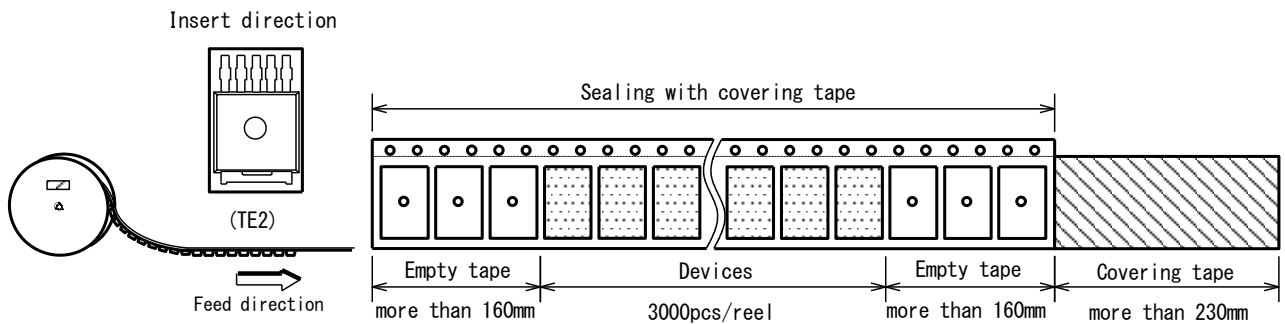
SYMBOL	DIMENSION	REMARKS
A	$6.9 \pm 0.1$	BOTTOM DIMENSION
B	$10.5 \pm 0.1$	BOTTOM DIMENSION
D0	$1.5^{+0.1}_0$	
D1	$1.5^{+0.1}_0$	
E	$1.75 \pm 0.1$	
F	$7.5 \pm 0.1$	
P0	$4.0 \pm 0.1$	
P1	$8.0 \pm 0.1$	
P2	$2.0 \pm 0.1$	
T	$0.3 \pm 0.1$	
T2	3.4 max	
W	$16.0 \pm 0.3$	
W1	13.5	THICKNESS 0.1max

## REEL DIMENSIONS

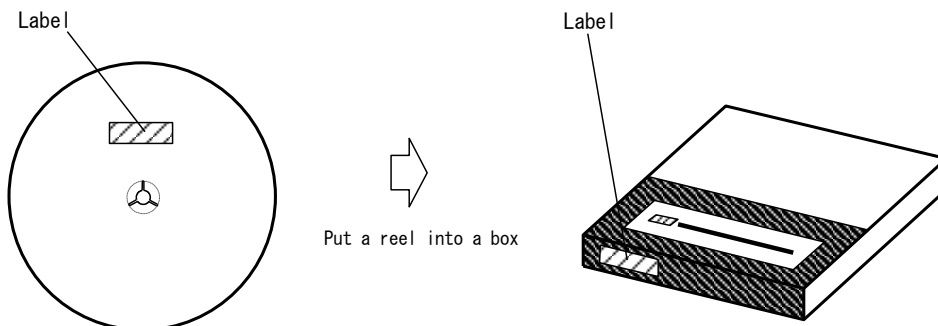


SYMBOL	DIMENSION
A	$\phi 330 \pm 2$
B	$\phi 80 \pm 1$
C	$\phi 13 \pm 0.5$
E	2
W	$17.5 \pm 0.5$
W1	$2 \pm 0.5$

## TAPING STATE

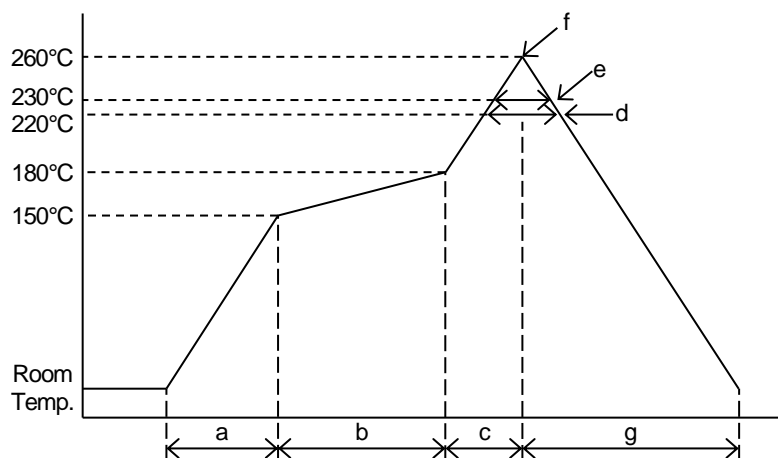


## PACKING STATE



## ■ RECOMMENDED MOUNTING METHOD

### INFRARED REFLOW SOLDERING PROFILE



a	Temperature ramping rate	1 to 4°C/s
b	Pre-heating temperature Pre-heating time	150 to 180°C 60 to 120s
c	Temperature ramp rate	1 to 4°C/s
d	220°C or higher time	shorter than 60s
e	230°C or higher time	shorter than 40s
f	Peak temperature	lower than 260°C
g	Temperature ramping rate	1 to 6°C/s

The temperature indicates at the surface of mold package.

## ■ REVISION HISTORY

DATE	REVISION	CHANGES
April 19, 2021	Ver.1.0	Initial release
October 1, 2024	Ver.2.0	Company name and logo changed to Nisshinbo Microdevices Inc.



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  - 8-2. Quality Warranty Remedies
 

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Note that such delivery or refund is sole and exclusive remedies to your company for the defective product.
  - 8-3. Remedies after Quality Warranty Period
 

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